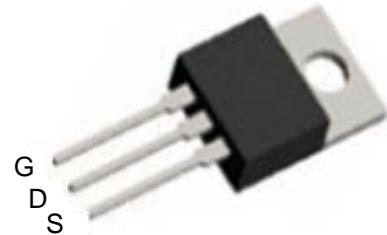


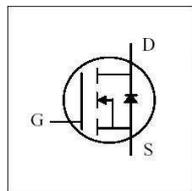
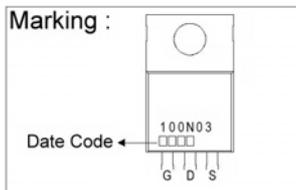
**N-Channel Enhancement MOSFET****VDS= 100V, ID= 52A****DESCRIPTION**

The YS100N03P is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

The YS100N03P meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

**TO-220****FEATURES**

- Low On-Resistance
- Low Input Capacitance
- Green Device Available
- Low Miller Charge
- 100% EAS Guaranteed

**Absolute Maximum Ratings**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D @ T_C=25^\circ C$	52	A
	$I_D @ T_C=100^\circ C$	33	A
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	180	A
Continuous Drain Current	$I_D @ T_A=25^\circ C$	7.5	A
	$I_D @ T_A=70^\circ C$	6	A
Total Power Dissipation	$P_D @ T_C=25^\circ C$	96.2	W
	$P_D @ T_A=25^\circ C$	2	W
Single Pulse Avalanche Energy, L=0.1mH	$E_{AS}$	24.2	mJ
Single Pulse Avalanche Current, L=0.1mH	$I_{AS}$	22	A
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 ~ +150	$^\circ C$

**Thermal Data**

Parameter	Symbol	Conditions	Max. Value	Unit
Thermal Resistance Junction-ambient <sup>2</sup>	$R_{\theta JA}$	Steady State	62	$^\circ C/W$
Thermal Resistance Junction-case <sup>2</sup>	$R_{\theta JC}$	Steady State	1.3	$^\circ C/W$

# DEVICE CHARACTERISTICS

## YS100N03P

### Electrical Characteristics (T<sub>j</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0, I <sub>D</sub> =250uA	100	-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1.2	1.8	2.5	V
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V	-	-	±100	nA
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =80V, V <sub>GS</sub> =0	-	-	1	uA
Static Drain-Source On-Resistance <sup>1</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	-	20	25	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	-	22	28.5	
Total Gate Charge <sup>1</sup>	Q <sub>g</sub>	I <sub>D</sub> =10A V <sub>DS</sub> =50V V <sub>GS</sub> =10V	-	34	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	6	-	
Gate-Drain ("Miller") Charge	Q <sub>gd</sub>		-	9	-	
Turn-on Delay Time <sup>1</sup>	T <sub>d(on)</sub>	V <sub>DS</sub> =50V V <sub>GS</sub> =10V R <sub>G</sub> =3Ω R <sub>L</sub> =5Ω	-	7	-	ns
Rise Time	T <sub>r</sub>		-	7	-	
Turn-off Delay Time	T <sub>d(off)</sub>		-	29	-	
Fall Time	T <sub>f</sub>		-	7	-	
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V V <sub>DS</sub> =30V f=1.0MHz	-	1325	-	pF
Output Capacitance	C <sub>oss</sub>		-	110	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	64	-	

### Guaranteed Avalanche Characteristics

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Single Pulse Avalanche Energy <sup>3</sup>	EAS	V <sub>DD</sub> =50V, L=0.1mH, I <sub>AS</sub> =16A	12.8	-	-	mJ

### Source-Drain Diode

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Diode Forward Voltage <sup>1</sup>	V <sub>SD</sub>	I <sub>S</sub> =10A, V <sub>GS</sub> =0V	-	-	1.3	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =10A, dI/dt=100A/μs, T <sub>J</sub> =25°C	-	32	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	200	-	nC

Notes: 1. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.

2. R<sub>θJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>θJC</sub> is guaranteed by design while R<sub>θCA</sub> is determined by the user's board design. R<sub>θJA</sub> shown below for single device operation on FR-4 in still air.

3. The Min. value is 100% EAS tested guarantee.

# DEVICE CHARACTERISTICS

## YS100N03P

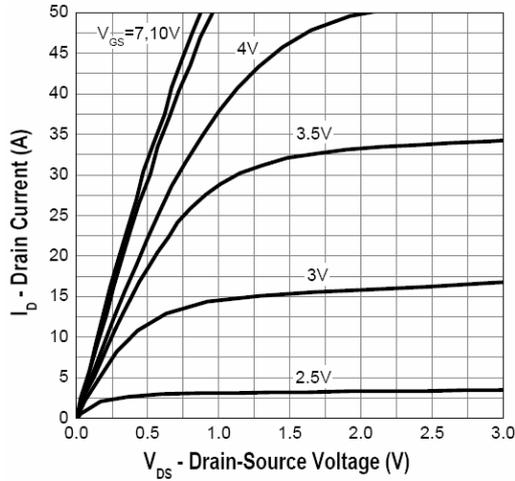


Fig.1 Typical Output Characteristics

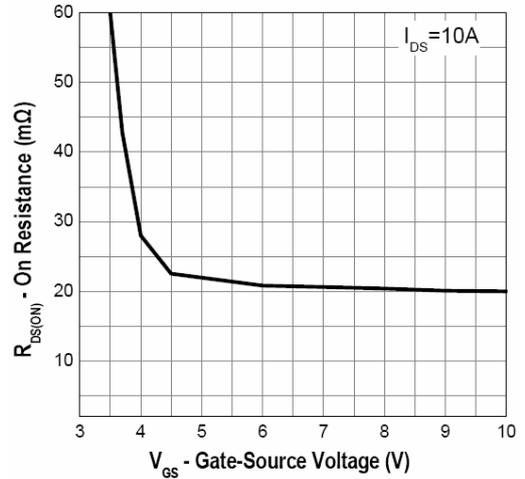


Fig.2 On-Resistance vs. G-S Voltage

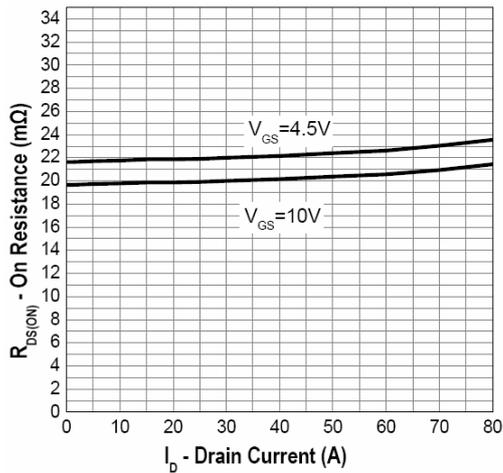


Fig.3 On-Resistance vs. Drain Current

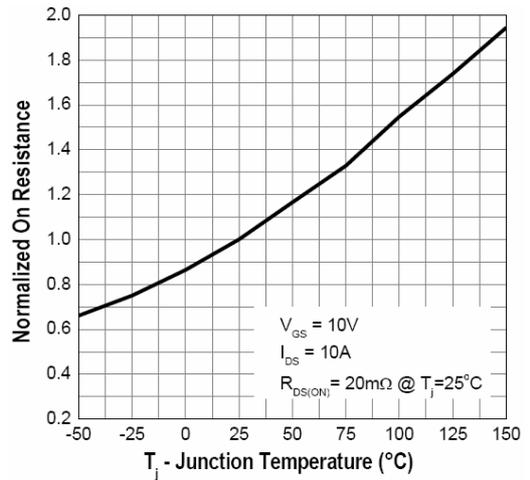


Fig.4 Normalized  $R_{DS(ON)}$  vs.  $T_J$

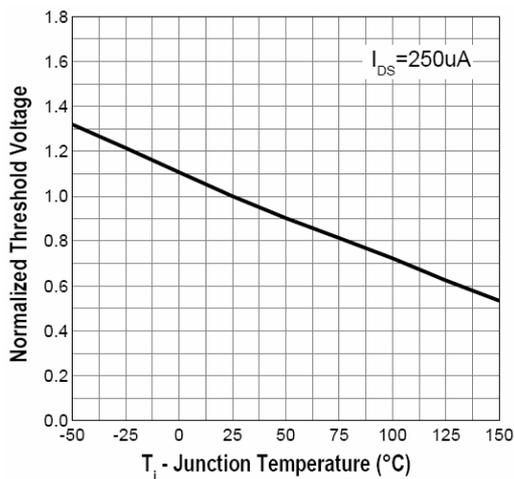


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

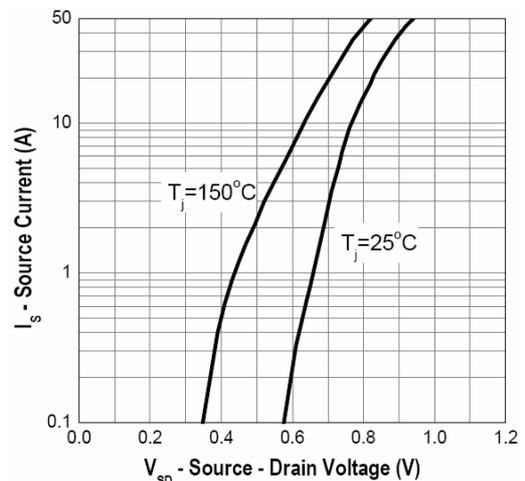


Fig.6 Forward Characteristics of Reverse

# DEVICE CHARACTERISTICS

## YS100N03P

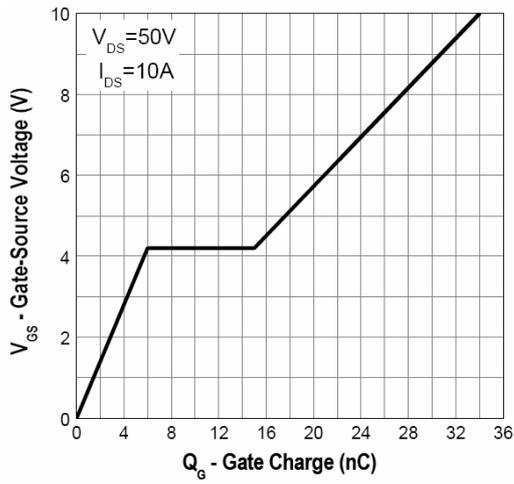


Fig.7 Gate Charge Characteristics

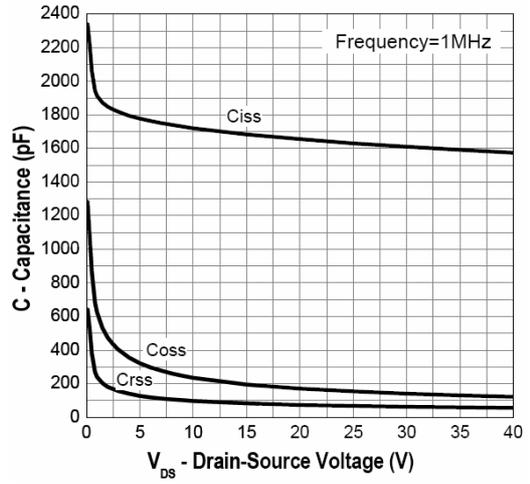


Fig.8 Capacitance Characteristics

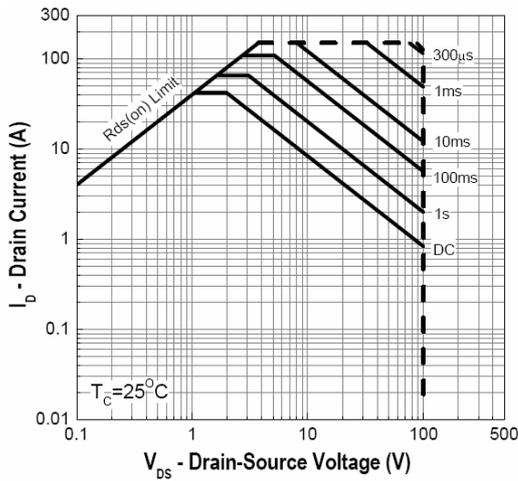


Fig.9 Safe Operating Area

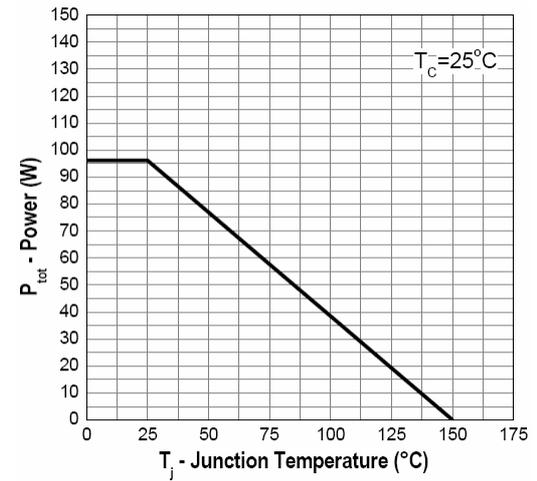


Fig.10 Power Dissipation

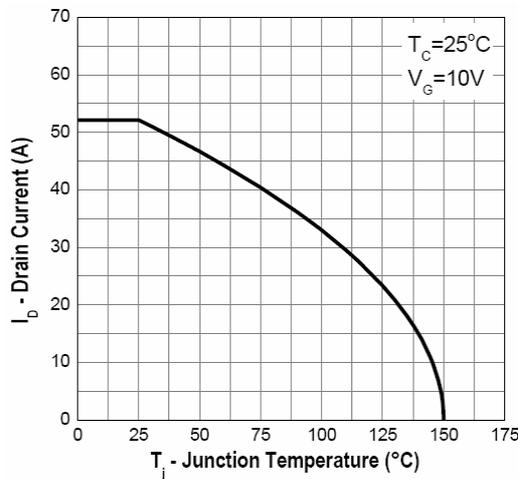


Fig.11 Drain Current vs.  $T_j$

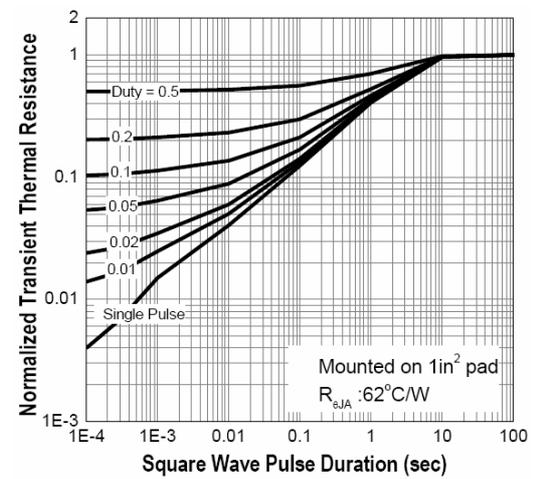
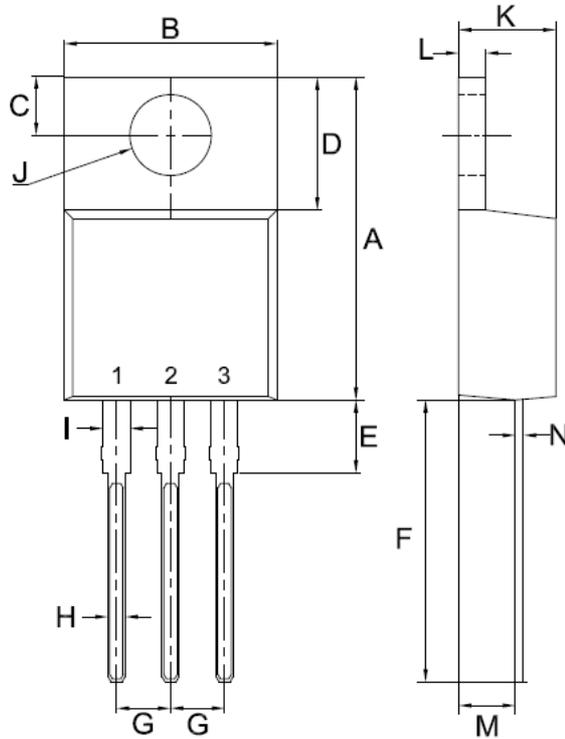


Fig.12 Transient Thermal Impedance

# PACKAGE OUTLINE & DIMENSIONS

YS100N03P

## TO-220 Mechanical Drawing



TO-220			
Unit : mm			
	min	typ	max
A	14.5		16.2
B	9.5		10.57
C	2.54		3
D	5.8		7.3
E	2.95		4.5
F	12.7		14
G	2.34		2.75
H	0.3		1.11
I	0.9		1.75
J	3.2		4.14
K	4.24		4.87
L	1		1.5
M	1.09		2.92
N	0.3		0.68